

L Number	Hits	Search Text	DB	Time stamp
1	2	4725511.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/07 15:49
2	6	4725511.URPN.	USPAT	2003/05/07 15:41
3	6	4725511.URPN.	USPAT	2003/05/07 15:41
4	43	428/620.ccls. and (picture or image)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/07 15:50
5	4	("3412575" "3515459" "3959527" "4094575").PN.	USPAT	2003/05/07 15:51
8	10	4604329.URPN.	USPAT	2003/05/07 15:52
9	11	("4512848" "4604329" "4634148" "4971646" "5190318" "5234537" "5267753" "5509553" "5509692" "5636874" "5660738").PN.	USPAT	2003/05/07 15:57
-	286	428/28.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 13:41
-	4	428/28.ccls. and magnet\$4	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 13:42
-	364	63/32.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 14:23
-	57	63/32.ccls. and layer\$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:35
-	3	4490440.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 15:12
-	0	GB2083842A.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 15:12
-	0	GB2083842A	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 15:13
-	1	GB-2083842-A.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 15:13
-	0	(63/32.ccls. and layer\$3) and strike	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:01

-	1	63/32.ccls. and strike	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:01
-	86392	CVD	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:04
-	6925	CVD and diamond\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:04
-	5039	(CVD and diamond\$2) and layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:08
-	4306	((CVD and diamond\$2) and layer) and substrate\$2	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:10
-	71	((((CVD and diamond\$2) and layer) and substrate\$2) and (gem\$7 or jewelry)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:20
-	19989	silicon and diamond	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:20
-	4964	(silicon and diamond) and wafer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:21
-	1560	((silicon and diamond) and wafer) and CVD	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:23
-	0	29820230.URPN.	USPAT	2002/06/18 16:23
-	0	20010049003.URPN.	USPAT	2002/06/18 16:26
-	0	9317593.URPN.	USPAT	2002/06/18 16:28
-	2	(63/32.ccls. and layer\$3) and clock	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:36
-	3	(63/32.ccls. and layer\$3) and watch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 16:36
-	123	corundum near3 layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 17:02

-	2	(corundum near3 layer) and CVD	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 17:02
-	80	CVD and corundum	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 17:03
-	23	("Re29420" "Re31526" "Re32111" "3736107" "3836392" "3837894" "3885063" "3917473" "3955038" "3977061" "4018631" "4035541" "4169913" "4180400" "4239536" "4268569" "4399168" "4463062" "4474849" "4619866" "4714660" "4749630" "4984940").PN.	USPAT	2002/06/18 17:15
-	4	("3412575" "3515459" "3959527" "4094575").PN.	USPAT	2002/06/18 17:22
-	6	4725511.URPN.	USPAT	2002/06/18 17:22
-	13	3539379.URPN.	USPAT	2002/06/18 17:26
-	56	(corundum and CVD) and coating	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/06/18 17:30